

Title (en)  
Decorating assembly comprising a modular magnetisation device

Title (de)  
Dekorationsanordnung mit einer modularen Magnetisierungsvorrichtung

Title (fr)  
Ensemble de conditionnement comportant un dispositif d'aimantation modulé

Publication  
**EP 2208620 A1 20100721 (FR)**

Application  
**EP 09179129 A 20091214**

Priority  
FR 0859006 A 20081223

Abstract (en)  
The assembly has a container that contains fluid composition having magnetic substances, and a magnetization device (8) to produce a pattern on a substrate i.e. nail (7), onto which the composition is deposited. The magnetization device has first and second magnets (10, 11), where one of the magnets is in the form of a flexible sheet. The magnets are partially superposed such that magnetic field lines of the first magnet are positioned at a right angle relative to magnetic field lines of the second magnet, where the sheet is made of a thermoplastic or resin material. An independent claim is also included for a method for decorating a substrate using a packaging assembly.

Abstract (fr)  
Ensemble comportant un récipient (1) contenant une composition fluide comportant des corps magnétiques et un dispositif d'aimantation (8) permettant de réaliser un motif sur un substrat (7) sur lequel ladite composition a été déposée, ce dispositif d'aimantation comportant un support (12) et deux aimants (10, 11) dont l'un au moins est sous forme de feuille souple, les deux aimants étant au moins partiellement superposés de sorte que les lignes de champs qu'ils génèrent en association l'un avec l'autre résultent de l'interférence entre les lignes de champs de chacun des aimants.

IPC 8 full level  
**B44C 1/00** (2006.01)

CPC (source: EP US)  
**A45D 29/22** (2013.01 - EP US); **A45D 34/04** (2013.01 - EP US); **A45D 34/045** (2013.01 - EP US); **A45D 40/18** (2013.01 - EP US); **B05D 3/207** (2013.01 - EP US); **B05D 5/061** (2013.01 - EP US); **B44C 1/00** (2013.01 - EP US)

Citation (search report)

- [A] WO 2008046702 A1 20080424 - SICPA HOLDING SA [CH], et al
- [A] EP 1759610 A1 20070307 - OREAL [FR]
- [A] EP 1493590 A1 20050105 - SICPA HOLDING SA [CH]
- [A] WO 2006054002 A1 20060526 - OREAL [FR], et al

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Designated contracting state (EPC)  
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO SE SI SK SM TR

Designated extension state (EPC)  
AL BA RS

DOCDB simple family (publication)  
**EP 2208620 A1 20100721**; **EP 2208620 B1 20111019**; AT E529270 T1 20111115; BR PI0907292 A2 20140107; ES 2375692 T3 20120305; FR 2940181 A1 20100625; FR 2940181 B1 20110513; JP 2010149518 A 20100708; JP 5606730 B2 20141015; US 2010156581 A1 20100624; US 8371311 B2 20130212

DOCDB simple family (application)  
**EP 09179129 A 20091214**; AT 09179129 T 20091214; BR PI0907292 A 20091221; ES 09179129 T 20091214; FR 0859006 A 20081223; JP 2009291224 A 20091222; US 64343709 A 20091221